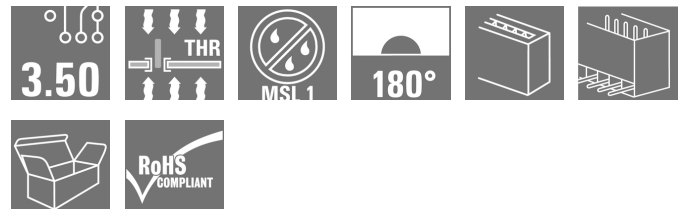
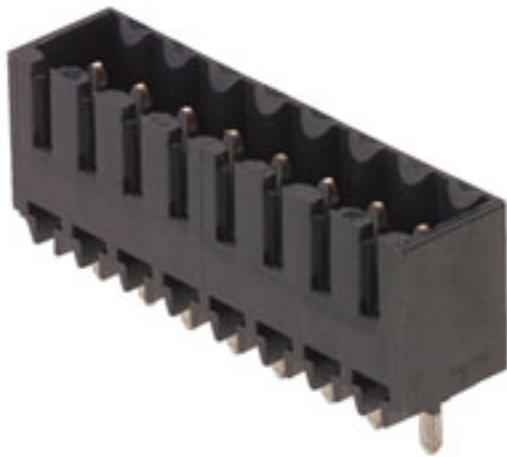


**OMNIMATE Signal - series BL/SL 3.50
SL-SMT 3.50/02/180G 3.2SN BK BX**

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com



High-temperature-resistant male header, 3.50 mm pitch.

- **Plugging direction parallel (90°), straight 180° or angled (135°) to PCB**
- **Housing variants: closed side (G), screw flange (F), solder flange (LF) or snap-on solder flange (RF)**
- **Optimised for the SMT process**
- **Pin length 3.2 mm universal for all soldering methods**
- **Pin length 1.5 mm optimised for reflow soldering methods**
- **Packed either in a box (BX) or tape-on-reel (RL)**
- **Male header can be coded**

General ordering data

Type	SL-SMT 3.50/02/180G 3.2SN BK BX
Order No.	1842320000
Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.50 mm, No. of poles: 2, 180°, Solder pin length (l): 3.2 mm, tinned, Black, Box
GTIN (EAN)	4032248353668
Qty.	100 pc(s).
Product data	IEC: 320 V / 15 A UL: 300 V / 10 A
Packaging	Box

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Technical data

Dimensions and weights

Width	8.4 mm	Width (inches)	0.331 inch
Height	14.3 mm	Height (inches)	0.563 inch
Height of lowest version	11.1 mm	Depth	7.5 mm
Depth (inches)	0.295 inch	Net weight	0.83 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 3.50	Type of connection	Solder connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.5 mm
Pitch in inches (P)	0.138 inch	Outgoing elbow	180°
No. of poles	2	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin length tolerance	0 / -0.3 mm
Tolerance of solder pin position	± 0.1 mm	Solder pin dimensions	d = 1.2 mm, Octagonal
Solder pin dimensions = d tolerance	0 / -0.03 mm	Solder eyelet hole diameter (D)	1.4 mm
Solder eyelet hole diameter tolerance (D)+ 0.1 mm		Outside diameter of solder pad	2.3 mm
Template aperture diameter	2.1 mm	L1 in mm	3.5 mm
L1 in inches	0.138 inch	Number of rows	1
Pin series quantity	1	Touch-safe protection acc. to DIN VDE 57 106	Safe from back-of-hand touch
Touch-safe protection acc. to DIN VDE 0470	IP 10	Volume resistance	4.50 mΩ
Can be coded	Yes	Plugging cycles	25
push-in force/pole	10 N	Withdrawal force per pole	8 N
Packaging	Box		

Material data

Insulating material	LCP GF	Colour	Black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
CTI	≥ 175	Insulation resistance	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact material	CuSn	Contact surface	tinned
Layer structure of solder connection	2-3 µm Ni / 5-7 µm Sn	Layer structure of plug contact	2-3 µm Ni / 5-7 µm Sn
Storage temperature, min.	-25 °C	Storage temperature, max.	55 °C
Max. relative humidity during storage	80 %	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. no. of poles (Tu=20°C)	15 A
Rated current, max. no. of poles (Tu=20°C)	12 A	Rated current, min. no. of poles (Tu=40°C)	13 A
Rated current, max. no. of poles (Tu=40°C)	10 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 100 A

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Technical data

Rated data acc. to CSA

Institute (CSA)		Certificate No. (CSA)	
		200039-1176845	
Rated voltage (Use group B)	300 V	Rated voltage (use group D)	300 V
Rated current (use group B)	10 A	Rated current (use group D)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Rated data acc. to UL 1059

Institute (UR)		Certificate No. (UR)	
		E60693	
Rated voltage (use group B)	300 V	Rated voltage (use group D)	300 V
Rated current (use group B)	10 A	Rated current (use group D)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Classifications

ETIM 3.0	EC001284	ETIM 4.0	EC002637
ETIM 5.0	EC002637	ETIM 6.0	EC002637
UNSPSC	30-21-18-10	eClass 5.1	27-26-07-04
eClass 6.2	27-26-07-04	eClass 7.1	27-44-04-02
eClass 8.1	27-44-04-02	eClass 9.0	27-44-04-02
eClass 9.1	27-44-04-02		

Notes

Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet D = 1.4+0.1mm • Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

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Technical data**Approvals**

Approvals



ROHS

Conform

DownloadsApproval/Certificate/Document of
Conformity[Declaration of the Manufacturer](#)

Brochure/Catalogue

[FL DRIVES EN](#)
[MB SMT EN](#)
[FL DRIVES DE](#)
[MB DEVICE MANUF. EN](#)
[CAT 2 PORTFOLIOGUIDE EN](#)
[FL BUILDING SAFETY EN](#)
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[FL_BASE_STATION_EN](#)
[FL ELEVATOR EN](#)
[FL POWER SUPPLY EN](#)
[FL 72H SAMPLE SER EN](#)
[PO OMNIMATE EN](#)

Engineering Data

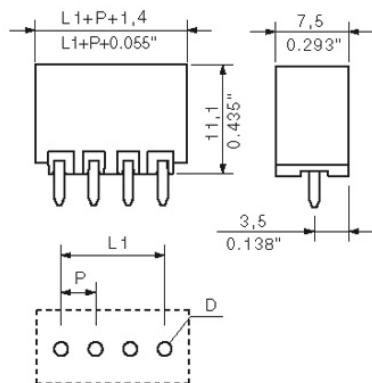
[SL-SMT.zip](#)

SMT white paper

[Download Whitepaper](#)

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Drawings**Dimensional drawing**

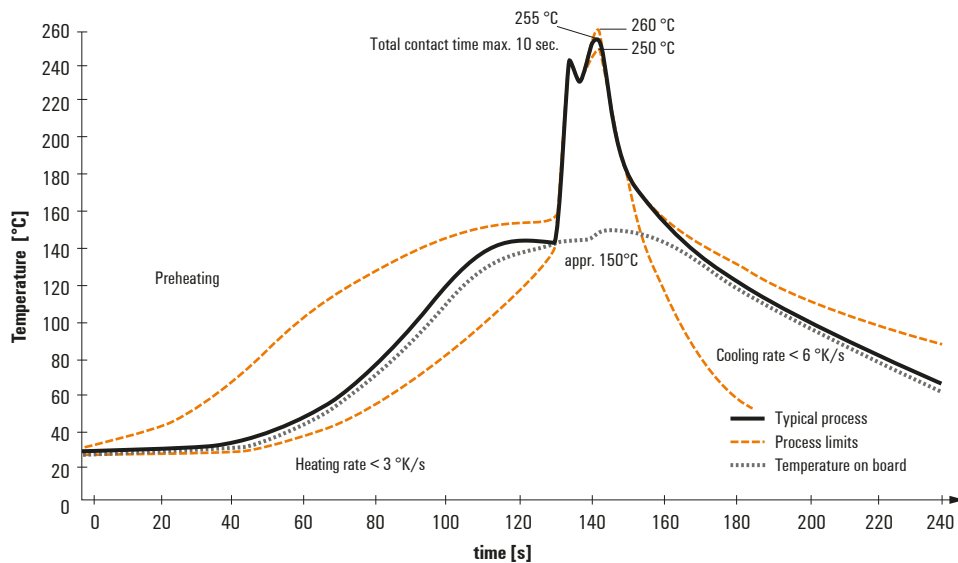
Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260 °C . In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16

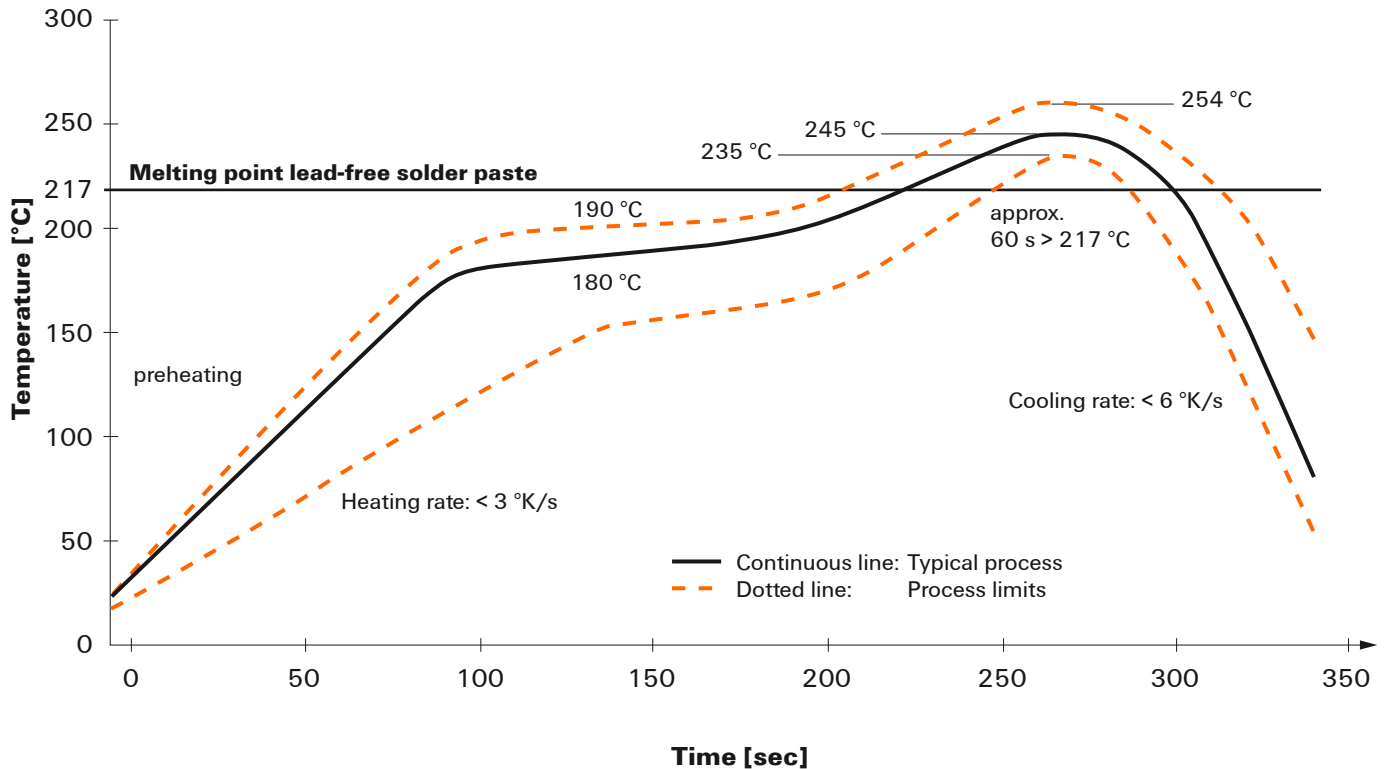
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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.